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IMPOSSIBLE BECOMES REALITY

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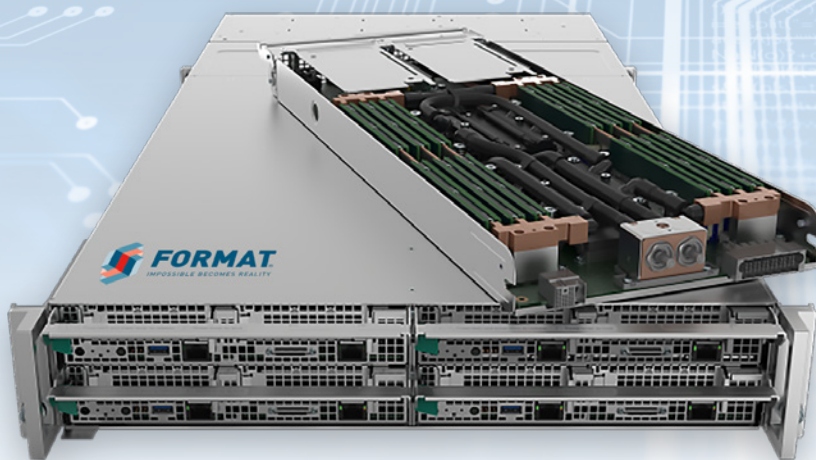
ul. Czereśniowa 130, 02-456 Warszawa

phone: +48 22 463-52-00

mail: [handlowy@format.com.pl](mailto:handlowy@format.com.pl)

# FormatTWIN ODYN P2484 LC

**Density Optimized System Solution Providing Leadership Performance for HPC and AI**

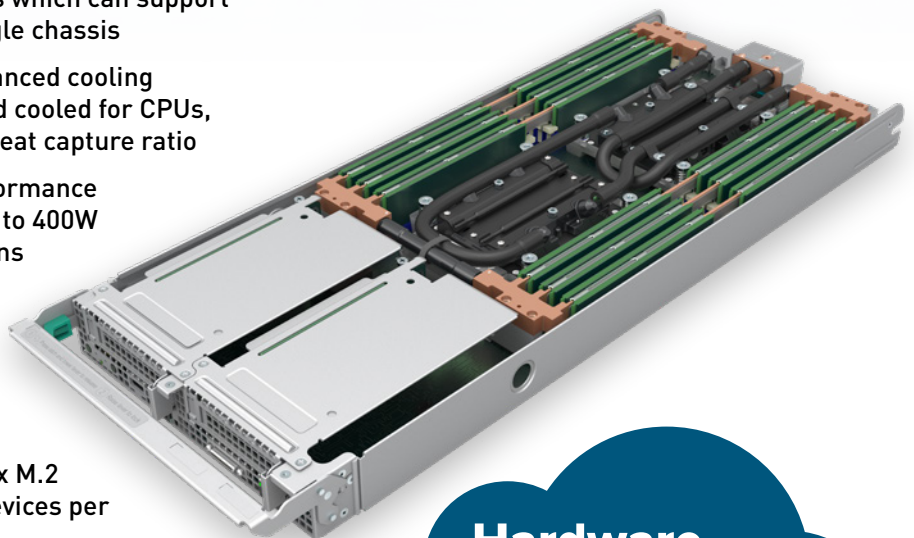


## Intel® Xeon® Platinum 9200 Processors Advanced Performance

- Leadership CPU performance per socket with Intel's highest core count, Intel® Xeon® Platinum 9200 processors
- Double the memory bandwidth for memory-intensive workloads with 12 memory channels per CPU, 24 memory channels per compute module
- New Intel® Deep Learning Boost Instructions for data analytics greatly accelerates inference performance
- Multi-Chip packaging optimized for density and performance

## FormatNode ODYN P024 LC - Density Optimized 2U Rack Server with Air-Cooled and Liquid-Cooled Options

- Up to 4 compute modules per 2U chassis which can support multiple compute module types in a single chassis
- 2 CPU compute module design with advanced cooling technology for high flow rate air or liquid cooled for CPUs, VRs, DIMMs, and memory VRs for high heat capture ratio
- Up to 350W processor TDP for high performance workloads in a 2U air cooled chassis, up to 400W processor TDP with liquid-cooled versions
- Up to 2 x16 PCIe slots in 1U compute modules, up to 4 x16 PCIe slots in 2U compute modules for network expansion options
- Support for 2x M.2 SATA/NVMe storage devices per 1U compute module, up to 2x M.2 SATA/NVMe and 2x U.2 NVMe storage devices per 2U compute module
- Hot-swappable compute modules, storage, fans, and power supplies



**Hardware  
Compatible  
with OpenStack  
Cloud**

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## Technical Specifications

Compute Module: FormatNode ODYN P024 LC	
<b>Chassis Form Factor</b>	2U Rack front IO
<b>Integrated Systems Available</b>	Yes
<b>Integrated BMC with IPMI</b>	2.0
<b>TDP</b>	350 W
<b>Included Items</b>	(1)S9200WK Compute Module (2)1U PCIe Riser (1) Liquid cooling sled solution (2) M.2 Heatsink
<b>Board Chipset</b>	Intel® C621 Chipset
<b>Description</b>	S9200WK Compute Module for use in Intel® Data Center Blocks featuring Intel® Xeon® Platinum 9200 processors housed in new 2U front I/O Intel® Server Chassis FC2000.
Memory Specifications	
<b>Max Memory Size</b>	3 TB
<b>Memory Types</b>	DDR4 RDIMM 2933
<b>Max # of Memory Channels</b>	24
Expansion Options	
<b>PCIe x16 Gen 3</b>	2
Package Specifications	
<b>Max CPU Configuration</b>	2
Advanced Technologies	
<b>Intel® Optane™ Memory Supported</b>	Yes

Server Chassis	
<b>Chassis Form Factor</b>	2U Front IO, 4 node Rack
<b>Chassis Dimensions</b>	16.93" x 36.61" x 3.44"
<b>Power Supply</b>	2100 W
<b>Power Supply Type</b>	AC
<b># of Power Supply Included</b>	3
<b>Redundant Fans</b>	Yes
<b>Redundant Power Supported</b>	Yes
Supplemental Information	
<b>Description</b>	Liquid Cooled 2U flexible multi node chassis with front IO, capable of supporting either two, three, or four independent warm-swap compute nodes and 3x hot-swap CRPS 2100W (Platinum) or 1600W (Titanium) PSUs.
Package Specifications	
<b>Max CPU Configuration</b>	8

